COINS is the premier conference devoted to omni-layer techniques for smart IoT systems, by identifying new perspectives and highlighting impending research issues and challenges. The special track “Blockchain and Internet of Things” covers (but is not limited to) the following topics:

- Recent development in Blockchain research
- Recent development in IoT research
- New Blockchain consensus protocols, platforms and development tools
- Throughout, latency and performance issues in Blockchain based IoT systems
- System design and implementation methods for Blockchain based IoT systems
- Blockchain in IoT device identity management and asset tracking
- Blockchain in IoT supply chain management
- Blockchain applications in IoT data privacy and security
- Blockchain in peer-to-peer and M2M communications
- IoT assisted Blockchain applications
- Blockchain applications in banking, real estate, healthcare and energy system
- Blockchain in Smart home, smart building, smart city applications
- Blockchain and IoT courses, curriculum and instructional tools

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Extended versions of selected best papers will be published in a special issue of the ISI indexed Elsevier journal “Microprocessors and Microsystems: Embedded Hardware Design” (MICPRO) having the 2016 Impact Factor as high as 1.025.

In order to conduct a blind review, no indication of the authors’ names should appear in the manuscript, references included.

**Important Dates**

- Submission Deadline: January 15, 2019
- Notification Date: January 31, 2019
- Camera-ready: February 15, 2019
- Conference Dates: May 5-7, 2019

**Grant**

COINS Executive Committee is pleased to announce registration grants for highly skilled students who have an accepted paper. We are especially looking forward to applications from Middle East, and Asia.

All questions about submissions should be emailed to Dr.-Ing. Farshad Firouzi (farshadfirouzi@gmail.com).